



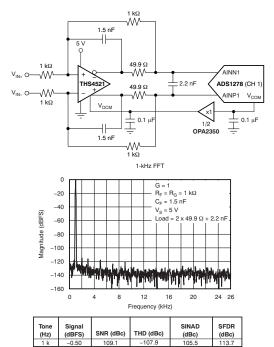
VERY LOW POWER, NEGATIVE RAIL INPUT, RAIL-TO-RAIL OUTPUT, FULLY DIFFERENTIAL AMPLIFIER

Check for Samples: THS4521, THS4522, THS4524

FEATURES

- · Fully Differential Architecture
- Bandwidth: 145 MHz
- Slew Rate: 490 V/µs
- HD_2 : -133 dBc at 10 kHz (1 V_{RMS} , $R_L = 1 k\Omega$)
- HD₃: -140 dBc at 10 kHz (1 V_{RMS}, R_L = 1 k Ω)
- Input Voltage Noise: 4.6 nV/√Hz (f = 100 kHz)
- THD+N: -112dBc (0.00025%) at 1 kHz (22-kHz BW, G = 1, 5 V_{PP})
- Open-Loop Gain: 119 dB
- · NRI-Negative Rail Input
- RRO—Rail-to-Rail Output
- Output Common-Mode Control (with Low Offset and Drift)
- Power Supply:
 - Voltage: +2.5 V (±1.25 V) to +5.5 V (±2.75 V)
 - Current: 1.14 mA/ch
- Power-Down Capability: 20 µA (typ)

THS4521 and ADS1278 Combined Performance



APPLICATIONS

- Low-Power SAR and $\Delta\Sigma$ ADC Drivers
- Low-Power Differential Drivers
- Low-Power Differential Signal Conditioning
- Low-Power, High-Performance Differential Audio Amplifiers

DESCRIPTION

The THS4521, THS4522, and THS4524 family of devices are very low-power, fully differential op amps with rail-to-rail output and an input common-mode range that includes the negative rail. These amplifiers are designed for low-power data acquisition systems and high-density applications where power dissipation is a critical parameter, and provide exceptional performance in audio applications.

The family includes single (THS4521), dual (THS4522), and quad (THS4524) versions.

These fully differential op amps feature accurate output common-mode control that allows for dc-coupling when driving analog-to-digital converters (ADCs). This control, coupled with an input common-mode range below the negative rail as well as rail-to-rail output, allows for easy interfacing between single-ended, ground-referenced signal sources. Additionally, these devices are ideally suited for driving both successive-approximation register (SAR) and delta-sigma ($\Delta\Sigma$) ADCs using only a single +2.5V to +5V and ground power supply.

The THS4521, THS4522, and THS4524 family of fully differential op amps is characterized for operation over the full industrial temperature range from -40°C to +85°C.

RELATED PRODUCTS

DEVICE	BW (MHz)	I _Q (mA)	THD (dBc) at 100 kHz	V <u>N</u>	RAIL- TO-RAIL				
THS4520	570	15.3	-114	2	Out				
THS4121	100	16	- 79	5.4	In/Out				
THS4130	150	16	-107	1.3	No				

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This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION(1)

PRODUCT	PACKAGE- LEAD	PACKAGE DESIGNATOR	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER	TRANSPORT MEDIA, QUANTITY
	SOIC-8	D		TH4521	THS4521ID	Rails, 75
THS4521	SOIC-8	D	-40°C to +85°C	1 1 1 4 3 2 1	THS4521IDR	Tape and reel, 2500
11154521	MSOP-8	DOK	-40 C t0 +85 C	4521	THS4521IDGKT	Tape and reel, 250
	MISOP-8	DGK			THS4521IDGKR	Tape and reel, 2500
TUC 4500	T000D 40	DW	40°C t05°C	TUC 4500	THS4522IPW	Rails, 90
1H54522	HS4522 TSSOP-16 PW -40°C to +85	-40°C to +85°C	-40°C to +85°C THS4522	THS4522IPWR	Tape and reel, 2000	
TUCAFOA	TCCOD 20	DDT	1000 1 0500	TUCAFOA	THS4524IDBT	Rails, 50
THS4524	TSSOP-38 DBT -	–40°C to +85°C	THS4524	THS4524IDBTR	Tape and reel, 2000	

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the relevant product folders at www.ti.com.

ABSOLUTE MAXIMUM RATINGS(1)

Over operating free-air temperature range (unless otherwise noted).

		THS4521, THS4522. THS4524	UNIT
Supply Vo	oltage, V _{S-} to V _{S+}	5.5	V
Input/Out	put Voltage, V _I (V _{IN±} , V _{OUT±} , V _{OCM} pins)	$(V_{S-}) - 0.7$ to $(V_{S+}) + 0.7V$	V
Differentia	al Input Voltage, V _{ID}	1	V
Output Co	urrent, I _O	100	mA
Input Cur	rent, I _I (V _{IN±} , V _{OCM} pins)	10	mA
Continuo	us Power Dissipation	See Thermal Characteristic Specifications	
Maximum	n Junction Temperature, T _J	+150	°C
Maximum	n Junction Temperature, T _J (continuous operation, long-term reliability)	+125	°C
Operating	Free-air Temperature Range, T _A	-40 to +85	°C
Storage T	Femperature Range, T _{STG}	-65 to +150	°C
	Human Body Model (HBM)	1300	V
ESD Rating:	Charge Device Model (CDM)	1000	V
rtating.	Machine Model (MM)	50	V

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



ELECTRICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 3.3 \text{ V}$

At V_{S+} = +3.3 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

		THS452	1, THS4522,	THS4524		TEST
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	LEVEL ⁽¹⁾
AC PERFORMANCE						
Small-Signal Bandwidth	$V_{OUT} = 100 \text{ mV}_{PP}, G = 1$		135		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, G = 2$		49		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, G = 5$		18.6		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, G = 10$		9.3		MHz	С
Gain Bandwidth Product	$V_{OUT} = 100 \text{ mV}_{PP}, G = 10$		93		MHz	С
Large-Signal Bandwidth	$V_{OUT} = 2 V_{PP}, G = 1$		95		MHz	С
Bandwidth for 0.1-dB Flatness	$V_{OUT} = 2 V_{PP}, G = 1$		20		MHz	С
Rising Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		420		V/µs	С
Falling Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		460		V/µs	С
Overshoot	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		1.2		%	С
Undershoot	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		2.1		%	С
Rise Time	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		4		ns	С
Fall Time	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		3.5		ns	С
Settling Time to 1%	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		13		ns	С
Harmonic Distortion						
2nd harmonic	$f = 1 \text{ kHz}, V_{OUT} = 1 V_{RMS}, G = 1^{(2)},$ differential input		-122		dBc	С
	$f = 1 MHz$, $V_{OUT} = 2 V_{PP}$, $G = 1$		-85		dBc	С
3rd harmonic	$f = 1 \text{ kHz}, V_{OUT} = 1 V_{RMS}, G = 1^{(2)},$ differential input		-141		dBc	С
	$f = 1 \text{ MHz}, V_{OUT} = 2 V_{PP}, G = 1$		-90		dBc	С
Second-Order Intermodulation Distortion	Two-tone, $f_1 = 2$ MHz, $f_2 = 2.2$ MHz, $V_{OUT} = 2-V_{PP}$ envelope		-83		dBc	С
Third-Order Intermodulation Distortion	Two-tone, $f_1 = 2$ MHz, $f_2 = 2.2$ MHz, $V_{OUT} = 2-V_{PP}$ envelope		-90		dBc	С
Input Voltage Noise	f > 10 kHz		4.6		nV/√ Hz	С
Input Current Noise	f > 100 kHz		0.6		pA/√ Hz	С
Overdrive Recovery Time	Overdrive = $\pm 0.5 \text{ V}$		80		ns	С
Output Balance Error	$V_{OUT} = 100 \text{ mV}, f \le 2 \text{ MHz (differential input)}$		-57		dB	С
Closed-Loop Output Impedance	f = 1 MHz (differential)		0.3		Ω	С
Channel-to-Channel Crosstalk (THS4522, THS4524)	f = 10 kHz, measured differentially		-125		dB	С
DC PERFORMANCE						
Open-Loop Voltage Gain (A _{OL})		100	116		dB	Α
Input-Referred Offset Voltage	$T_A = +25^{\circ}C$		±0.2	±2	mV	Α
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±0.5	±3.5	mV	В
Input offset voltage drift ⁽³⁾	$T_A = -40^{\circ}C$ to $+85^{\circ}C$		±2		μV/°C	С
Input Bias Current	$T_A = +25^{\circ}C$		0.65	0.85	μA	В
	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		0.75	0.95	μA	В
Input bias current drift ⁽³⁾	$T_A = -40^{\circ}C$ to $+85^{\circ}C$		±1.75	±2	nA/°C	В
Input Offset Current	$T_A = +25^{\circ}C$		±30	±180	nA	В
	$T_A = -40^{\circ}C$ to $+85^{\circ}C$		±30	±215	nA	В
Input offset current drift(3)	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±100	±600	pA/°C	В

⁽¹⁾ Test levels: **(A)** 100% tested at +25°C. Over temperature limits set by characterization and simulation. **(B)** Limits set by characterization and simulation. **(C)** Typical value only for information.

⁽²⁾ Not directly measureable; calculated using noise gain of 101 as described in the Applications section, Audio Performance.

⁽³⁾ Input Offset Voltage Drift, Input Bias Current Drift, and Input Offset Current Drift are average values calculated by taking data at -40°C and +85°C, computing the difference, and dividing by 125.



At V_{S+} = +3.3 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

INPUT Common-Mode Input Common-Mode Input Common-Mode Reject Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay Turn-Off Time Delay	t Voltage High ction Ratio (CMRR) (for linear operation) Voltage Current, per channel	CONDITIONS $T_{A} = +25^{\circ}C$ $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $T_{A} = +25^{\circ}C$ $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $T_{A} = +25^{\circ}C$ $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $T_{A} = -40^{\circ}C \text{ to } +85^{\circ}C$ $R_{L} = 50 \Omega$	1.9 1.8 80 3.0 2.95	TYP -0.2 -0.1 2 1.9 100 110 1.5 0.08 0.09 3.1 3.05 ±35	0.15 0.2	V V V V dB kΩ pF V V V V V V V V V V V V V V V V V V V	A B A C C
Common-Mode Input Common-Mode Reject Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	t Voltage High ction Ratio (CMRR) (for linear operation) Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	1.8 80 3.0 2.95	-0.1 2 1.9 100 110 1.5 0.08 0.09 3.1 3.05	0.15	V V V dB kΩ pF	B A B A C
Common-Mode Input Common-Mode Reject Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating \(\) Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	t Voltage High ction Ratio (CMRR) (for linear operation) Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	1.8 80 3.0 2.95	-0.1 2 1.9 100 110 1.5 0.08 0.09 3.1 3.05	0.15	V V V dB kΩ pF	B A B A C
Common-Mode Reject Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	ction Ratio (CMRR) (for linear operation) Voltage Current, per channel	$T_A = +25^{\circ}C$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = -40^{\circ}C$ to $+85^{\circ}C$ $R_L = 50 \Omega$ $T_A = +25^{\circ}C$	1.8 80 3.0 2.95	2 1.9 100 110 1.5 0.08 0.09 3.1 3.05	0.15	V V dB kΩ pF V V	A B A C
Common-Mode Reject Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	ction Ratio (CMRR) (for linear operation) Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	1.8 80 3.0 2.95	1.9 100 110 1.5 0.08 0.09 3.1 3.05		V dB kΩ pF V V	B A C
Common-Mode Reject Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	ction Ratio (CMRR) (for linear operation) Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	3.0 2.95	1.9 100 110 1.5 0.08 0.09 3.1 3.05		dB kΩ pF V V	A C A B
Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating \(\) Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	(for linear operation) Voltage Current, per channel	$T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$ $R_L = 50 \Omega$	3.0 2.95	100 110 1.5 0.08 0.09 3.1 3.05		kΩ∥pF	A C A B
Input Resistance OUTPUT Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating Valuescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	(for linear operation) Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	3.0 2.95	0.08 0.09 3.1 3.05		kΩ∥pF	C A B A
Output Voltage Low Output Voltage High Output Current Drive POWER SUPPLY Specified Operating \(\) Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	2.95	0.08 0.09 3.1 3.05		V V	B A
Output Voltage High Output Current Drive POWER SUPPLY Specified Operating \(\) Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curre Power Down Quiesce Turn-On Time Delay	Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	2.95	0.09 3.1 3.05		V	B A
Output Voltage High Output Current Drive POWER SUPPLY Specified Operating \(\) Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curre Power Down Quiesce Turn-On Time Delay	Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	2.95	3.1 3.05	0.2	V	Α
Output Current Drive POWER SUPPLY Specified Operating Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	Voltage Current, per channel	$T_A = +25^{\circ}\text{C}$ $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	2.95	3.1 3.05			Α
Output Current Drive POWER SUPPLY Specified Operating Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	Voltage Current, per channel	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $R_L = 50 \ \Omega$ $T_A = +25^{\circ}\text{C}$	2.95	3.05			
POWER SUPPLY Specified Operating \ Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Thres Disable Voltage Thre Disable Pin Bias Curn Power Down Quiesce Turn-On Time Delay	Voltage Current, per channel	$R_L = 50 \Omega$ $T_A = +25^{\circ}C$				•	
POWER SUPPLY Specified Operating \ Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Thres Disable Voltage Thre Disable Pin Bias Curn Power Down Quiesce Turn-On Time Delay	Voltage Current, per channel	T _A = +25°C	2.5	100		mA	С
Specified Operating \ Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Three Disable Voltage Three Disable Pin Bias Curn Power Down Quiesce Turn-On Time Delay	Current, per channel	1	2.5	1		IIIA	
Quiescent Operating Power-Supply Reject POWER DOWN Enable Voltage Thres Disable Voltage Thre Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	Current, per channel	1			5.5	V	В
Power-Supply Reject POWER DOWN Enable Voltage Thres Disable Voltage Thre Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	·	1	0.9	1.0	1.2	mA	A
POWER DOWN Enable Voltage Thres Disable Voltage Thre Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	tion Ratio (±PSRR)						
POWER DOWN Enable Voltage Thres Disable Voltage Thre Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	lion Ralio (±PSRR)	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	0.85 80	1.0	1.25	mA dB	В
Enable Voltage Thres Disable Voltage Thre Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay			80	100		uв	A
Disable Voltage Thre Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay	ah ald	Assured <i>on</i> above 2.1 V		1.6	2.1	V	۸
Disable Pin Bias Curr Power Down Quiesce Turn-On Time Delay			0.7	1.6	2.1		A
Power Down Quiesce Turn-On Time Delay		Assured off below 0.7 V	0.7	1.6		V	A
Turn-On Time Delay				1		μA	С
	ent Current			10		μA	С
Turn-Off Time Delay		Time to V_{OUT} = 90% of final value, V_{IN} = 2 V, R_L = 200 Ω		108		ns	В
		Time to V_{OUT} = 10% of original value, V_{IN} = 2 V , R_L = 200 Ω		88		ns	В
V _{OCM} VOLTAGE CO	NTROL						
Small-Signal Bandwid	dth			23		MHz	С
Slew Rate				55		V/µs	С
Gain			0.98	0.99	1.02	V/V	Α
Common-Mode Offse	et Voltage from V _{OCM} Input	Measured at V_{OUT} with V_{OCM} input driven, $V_{OCM} = 1.65 \text{ V} \pm 0.5 \text{ V}$		±2.5	±4	mV	В
Input Bias Current		$V_{OCM} = 1.65 \text{ V} \pm 0.5 \text{ V}$		±5	±8	μA	В
V _{OCM} Voltage Range			1	0.8 to 2.5	2.3	V	Α
Input Impedance				72 1.5		kΩ∥pF	С
Default Output Comm (V _{S+} - V _{S-})/2	non-Mode Voltage Offset from	Measured at V _{OUT} with V _{OCM} input open		±1.5	±5	mV	Α
THERMAL CHARAC	CTERISTICS						
Specified Operating F	Range, All Packages			-40 to +85		°C	С
Thermal Resistance,	-	Junction-to-ambient					
THS4521 D	SO-8			194		°C/W	С
DGK				269		°C/W	С
THS4522 PW	MSOP-8			116		°C/W	С
THS4524 DBT	MSOP-8 TSSOP-16	1		81		°C/W	С



ELECTRICAL CHARACTERISTICS: $V_{S+} - V_{S-} = 5 \text{ V}$

At V_{S+} = +5 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_F = 1 k Ω , R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, input and output referenced to midsupply, unless otherwise noted.

·		THS452	1, THS4522,	THS4524		TEST
PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	LEVEL ⁽¹⁾
AC PERFORMANCE						
Small-Signal Bandwidth	$V_{OUT} = 100 \text{ mV}_{PP}, G = 1$		145		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, G = 2$		50		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, G = 5$		20		MHz	С
	$V_{OUT} = 100 \text{ mV}_{PP}, G = 10$		9.5		MHz	С
Gain Bandwidth Product	$V_{OUT} = 100 \text{ mV}_{PP}, G = 10$		95		MHz	С
Large-Signal Bandwidth	$V_{OUT} = 2 V_{PP}, G = 1$		145		MHz	С
Bandwidth for 0.1-dB Flatness	$V_{OUT} = 2 V_{PP}, G = 1$		30		MHz	С
Rising Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		490		V/µs	С
Falling Slew Rate (Differential)	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		600		V/µs	С
Overshoot	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		1		%	С
Undershoot	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		2.6		%	С
Rise Time	V_{OUT} = 2-V Step, G = 1, R _L = 200 Ω		3.4		ns	С
Fall Time	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		3		ns	С
Settling Time to 1%	V_{OUT} = 2-V Step, G = 1, R_L = 200 Ω		10		ns	С
Harmonic Distortion						
2nd harmonic	$f = 1 \text{ kHz}, V_{OUT} = 1 V_{RMS}, G = 1^{(2)},$ differential input		-122		dBc	С
	f = 1 MHz, V _{OUT} = 2 V _{PP} , G = 1		-85		dBc	С
3rd harmonic	$f = 1 \text{ kHz}, V_{OUT} = 1 V_{RMS}, G = 1^{(2)},$ differential input		-141		dBc	С
	$f = 1 \text{ MHz}, V_{OUT} = 2 V_{PP}, G = 1$		-91		dBc	С
Second-Order Intermodulation Distortion	Two-tone, $f_1 = 2$ MHz, $f_2 = 2.2$ MHz, $V_{OUT} = 2 \cdot V_{PP}$ envelope		-86		dBc	С
Third-Order Intermodulation Distortion	Two-tone, $f_1 = 2$ MHz, $f_2 = 2.2$ MHz, $V_{OUT} = 2 \cdot V_{PP}$ envelope		-93		dBc	С
Input Voltage Noise	f > 10 kHz		4.6		nV/√ Hz	С
Input Current Noise	f > 100 kHz		0.6		pA/√ Hz	С
SNR	V _{OUT} = 5 V _{PP} , 20 Hz to 22 kHz BW, differential input		114		dBc	С
THD+N	f = 1 kHz , V_{OUT} = 5 V_{PP} , 20 Hz to 22 kHz BW, differential input		112		dBc	С
Overdrive Recovery Time	Overdrive = $\pm 0.5 \text{ V}$		75		ns	С
Output Balance Error	V _{OUT} = 100 mV, f < 2 MHz, V _{IN} differential		– 57		dB	С
Closed-Loop Output Impedance	f = 1 MHz (differential)		0.3		Ω	С
Channel-to-Channel Crosstalk (THS4522. THS4524)	f = 10 kHz, measured differentially		-125		dB	С
DC PERFORMANCE						
Open-Loop Voltage Gain (A _{OL})		100	119		dB	Α
Input-Referred Offset Voltage	$T_A = +25^{\circ}C$		±0.24	±2	mV	Α
	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		±0.5	±3.5	mV	В
Input offset voltage drift ⁽³⁾	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		±2		μV/°C	С
Input Bias Current	T _A = +25°C		0.7	0.9	μA	В
	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		0.9	1.1	μA	В
Input bias current drift (3)	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		±1.8	±2.2	nA/°C	В

⁽¹⁾ Test levels: **(A)** 100% tested at +25°C. Over temperature limits set by characterization and simulation. **(B)** Limits set by characterization and simulation. **(C)** Typical value only for information.

⁽²⁾ Not directly measureable; calculated using noise gain of 101 as described in the Applications section, Audio Performance.

⁽³⁾ Input Offset Voltage Drift, Input Bias Current Drift, and Input Offset Current Drift are average values calculated by taking data at -40°C and +85°C, computing the difference, and dividing by 125.



At V_{S+} = +5 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_F = 1 k Ω , R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, input and output referenced to midsupply, unless otherwise noted.

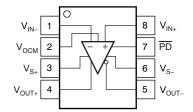
			THS452	1, THS4522,	THS4524		TEST
	PARAMETER	CONDITIONS	MIN	TYP	MAX	UNIT	LEVEL ⁽¹⁾
Input Offset C	Current	T _A = +25°C		±30	±180	nA	В
		$T_A = -40^{\circ}C$ to $+85^{\circ}C$		±30	±215	nA	В
	Input offset current drift ⁽⁴⁾	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$		±100	±600	pA/°C	В
INPUT							
Common-Moo	de Input Voltage Low	T _A = +25°C		-0.2	-0.1	V	Α
		$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$		-0.1	0	V	В
Common-Moo	de Input Voltage High	T _A = +25°C	3.6	3.7		V	Α
		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	3.5	3.6		V	В
Common-Moo	de Rejection Ratio (CMRR)		80	102		dB	Α
Input Impeda	nce			100 0.7		kΩ∥pF	С
OUTPUT							
Output Voltag	ge Low	T _A = +25°C		0.10	0.15	V	Α
		$T_A = -40$ °C to +85°C		0.115	0.2	V	В
Output Voltag	ge High	T _A = +25°C	4.7	4.75		V	Α
		$T_A = -40$ °C to +85°C	4.65	4.7		V	В
Output Curre	nt Drive (for linear operation)	$R_L = 50 \Omega$		±55		mA	С
POWER SUP	PPLY	-					
Specified Ope	erating Voltage		2.5		5.5	V	В
Quiescent Op	perating Current, per channel	T _A = +25°C	0.95	1.14	1.25	mA	Α
		$T_A = -40$ °C to +85°C	0.9	1.15	1.3	mA	В
Power-Supply Rejection Ratio (±PSRR)		· ·	80	100		dB	Α
POWER DOV							
Enable Voltage Threshold		Ensured on above 2.1 V		1.6	2.1	V	Α
Disable Voltage Threshold		Ensured off below 0.7 V	0.7	1.6		V	Α
Disable Pin Bias Current				1		μA	С
Power Down Quiescent Current				20		μA	С
Turn-On Time		Time to V_{OUT} = 90% of final value, V_{IN} = 2 V, R_L = 200 Ω		70		ns	В
Turn-Off Time Delay		Time to V_{OUT} = 10% of original value, V_{IN} = 2 V, R_L = 200 Ω		60		ns	В
V _{OCM} VOLTA	GE CONTROL						
Small-Signal	Bandwidth			23		MHz	С
Slew Rate				55		V/µs	С
Gain			0.98	0.99	1.02	V/V	Α
Common-Moo	de Offset Voltage from V _{OCM} Input	V _{OCM} = 2.3V ±1 V		±5	±9	mV	В
Input Bias Cu	ırrent	$V_{OCM} = 2.5V \pm 1 V$		±20	±25	μΑ	В
V _{OCM} Voltage	Range		1	0.8 to 4.2	4	V	Α
Input Impedance				46 1.5		kΩ∥pF	С
Default Output (V _{S+} - V _{S-})/2	ut Common-Mode Voltage Offset f	Measured at V _{OUT} with V _{OCM} input open		±1	±5	mV	А
THERMAL C	HARACTERISTICS						
Specified Operating Range All Packages			-40		+85	°C	С
Thermal Resi	istance, θ _{JA}	Junction-to-ambient					
THS4521	D SO-8			194		°C/W	С
	DGK MSOP-8			269		°C/W	С
THS4522	PW TSSOP-16			116		°C/W	С
THS4524	DBT TSSOP-38			81		°C/W	С

⁽⁴⁾ Input Offset Voltage Drift, Input Bias Current Drift, and Input Offset Current Drift are average values calculated by taking data at -40°C and +85°C, computing the difference, and dividing by 125.

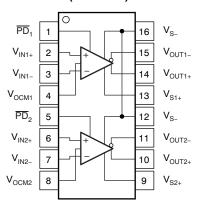


DEVICE INFORMATION

THS4521 SOIC-8, MSOP-8 (D, DGK PACKAGES) (TOP VIEW)



THS4522 TSSOP-16 (PW PACKAGE) (TOP VIEW)



TERMINAL FUNCTIONS: THS4521

SOIC-8, MSOP-8		
PIN NO.	NAME	DESCRIPTION
1	V_{IN-}	Inverting amplifier input
2	V_{OCM}	Common-mode voltage input
3	V_{S+}	Amplifier positive power-supply input
4	V_{OUT+}	Noninverting amplifier output
5	V_{OUT-}	Inverting amplifier output
6	V_{S-}	Amplifier negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
7	PD	Power down. \overline{PD} = logic low puts device into low-power mode. \overline{PD} = logic high or open for normal operation.
8	V _{IN+}	Noninverting amplifier input

TERMINAL FUNCTIONS: THS4522

TSSOP-16		
PIN NO.	NAME	DESCRIPTION
1	PD ₁	Power down 1. \overline{PD} = logic low puts device into low-power mode. \overline{PD} = logic high or open for normal operation.
2	V_{IN1+}	Noninverting amplifier 1 input
3	V_{IN1-}	Inverting amplifier 1 input
4	V _{OCM1}	Common-mode voltage input 1
5	PD ₂	Power down 2. \overline{PD} = logic low puts device into low-power mode. \overline{PD} = logic high or open for normal operation.
6	V_{IN2+}	Noninverting amplifier 2 input
7	V_{IN2-}	Inverting amplifier 2 input
8	V_{OCM2}	Common-mode voltage input 2
9	V _{S+2}	Amplifier 2 positive power-supply input
10	V _{OUT2+}	Noninverting amplifier 2 output
11	V _{OUT2}	Inverting amplifier 2 output
12	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.
13	V _{S+1}	Amplifier 1 positive power-supply input
14	V _{OUT1+}	Noninverting amplifier 1 output
15	V _{OUT1-}	Inverting amplifier 1 output

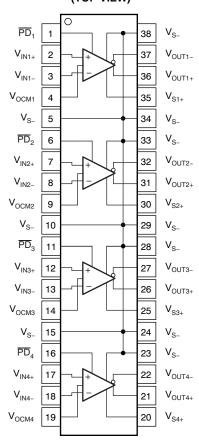
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TERMINAL FUNCTIONS: THS4522 (continued)

TSSOP-16		
PIN NO.	NAME	DESCRIPTION
16	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.

THS4524 TSSOP-38 (DBT PACKAGE) (TOP VIEW)





TERMINAL FUNCTIONS: THS4524

TSSC	OP-38	TERMINAL FUNCTIONS: THS4524
PIN NO.	NAME	DESCRIPTION
1	PD ₁	Power down 1. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
2	V _{IN1+}	Noninverting amplifier 1 input
3	V _{IN1} _	Inverting amplifier 1 input
4	V _{OCM1}	Common-mode voltage input 1
5	V _{S-}	Negative power-supply input. Note that V _S is tied together on multi-channel devices.
6	PD ₂	Power down 2. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
7	V_{IN2+}	Noninverting amplifier 2 input
8	V_{IN2-}	Inverting amplifier 2 input
9	V_{OCM2}	Common-mode voltage input 2
10	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
11	PD ₃	Power down 3. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
12	V _{IN3+}	Noninverting amplifier 3 input
13	V_{IN3-}	Inverting amplifier 3 input
14	V_{OCM3}	Common-mode voltage input 3
15	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
16	PD ₄	Power down 4. \overline{PD} = logic low puts channel into low-power mode. \overline{PD} = logic high or open for normal operation.
17	V_{IN4+}	Noninverting amplifier 4 input
18	V_{IN4-}	Inverting amplifier 4 input
19	V_{OCM4}	Common-mode voltage input 4
20	V_{S4+}	Amplifier 4 positive power-supply input
21	V_{OUT4+}	Noninverting amplifier 4 output
22	V_{OUT4-}	Inverting amplifier 4 output
23	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
24	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
25	V_{S3+}	Amplifier 3 positive power-supply input
26	V _{OUT3+}	Noninverting amplifier3 output
27	V _{OUT3}	Inverting amplifier3 output
28	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
29	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
30	V_{S2+}	Amplifier 2 positive power-supply input
31	V _{OUT2+}	Noninverting amplifier 2 output
32	V_{OUT2-}	Inverting amplifier 2 output
33	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
34	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.
35	V _{S1+}	Amplifier 1 positive power-supply input
36	V _{OUT1+}	Noninverting amplifier 1 output
37	V _{OUT1}	Inverting amplifier 1 output
38	V_{S-}	Negative power-supply input. Note that V_{S-} is tied together on multi-channel devices.



TYPICAL CHARACTERISTICS

Table of Graphs: $V_{S+} - V_{S-} = 3.3 \text{ V}$

TITLE	FIGURE
Small-Signal Frequency Response	Figure 1
Large-Signal Frequency Response	Figure 2
Large- and Small-Signal Pulse Response	Figure 3
Slew Rate vs V _{OUT} Step	Figure 4
Overdrive Recovery	Figure 5
10-kHz Output Spectrum on AP Analyzer	Figure 6
Harmonic Distortion vs Frequency	Figure 7
Harmonic Distortion vs Output Voltage at 1 MHz	Figure 8
Harmonic Distortion vs Gain at 1 MHz	Figure 9
Harmonic Distortion vs Load at 1 MHz	Figure 10
Harmonic Distortion vs V _{OCM} at 1 MHz	Figure 11
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Single-Ended Output Voltage Swing vs Load Resistance	Figure 13
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Turn-on Time	Figure 19
Turn-off Time	Figure 20
Input-Referred Voltage Noise and Current Noise Spectral Density	Figure 21
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Output Balance Error vs Frequency	Figure 23
V _{OCM} Small-Signal Frequency Response	Figure 24
V _{OCM} Large-Signal Frequency Response	Figure 25
V _{OCM} Input Impedance vs Frequency	Figure 26



Table of Graphs: $V_{S+} - V_{S-} = 5 \text{ V}$

TITLE	FIGURE
Small-Signal Frequency Response	Figure 27
Large-Signal Frequency Response	Figure 28
Large- and Small-Signal Pulse Response	Figure 29
Slew Rate vs V _{OUT} Step	Figure 30
Overdrive Recovery	Figure 31
10-kHz Output Spectrum on AP Analyzer	Figure 32
Harmonic Distortion vs Frequency	Figure 33
Harmonic Distortion vs Output Voltage at 1 MHz	Figure 34
Harmonic Distortion vs Gain at 1 MHz	Figure 35
Harmonic Distortion vs Load at 1 MHz	Figure 36
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Two-Tone, Second- and Third-Order Intermodulation Distortion vs Frequency	Figure 38
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Main Amplifier Differential Output Impedance vs Frequency	Figure 40
Frequency Response vs C_{LOAD} ($R_{LOAD} = 1 \text{ k}\Omega$)	Figure 41
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THS4522, THS4524 Crosstalk (Measured Differentially)	Figure 44
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Input-Referred Voltage Noise and Current Noise Spectral Density	Figure 47
Main Amplifier Differential Open-Loop Gain and Phase	Figure 48
Output Balance Error vs Frequency	Figure 49
V _{OCM} Small-Signal Frequency Response	Figure 50
V _{OCM} Large-Signal Frequency Response	Figure 51
V _{OCM} Input Impedance vs Frequency	Figure 52



At $V_{S+} = +3.3 \text{ V}$, $V_{S-} = 0 \text{ V}$, $V_{OCM} = \text{open}$, $V_{OUT} = 2 \text{ V}_{PP}$ (differential), $R_L = 1 \text{ k}\Omega$ differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

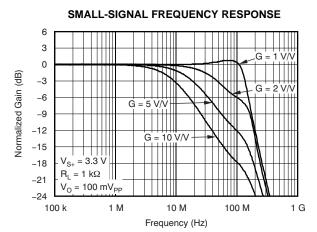


Figure 1.

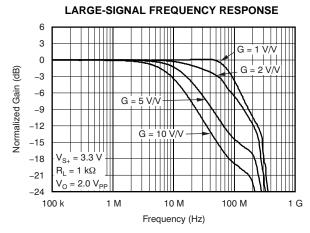


Figure 2.

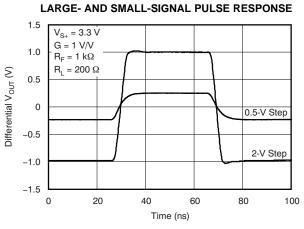


Figure 3.

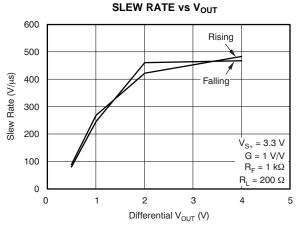


Figure 4.

10-kHz OUTPUT SPECTRUM ON

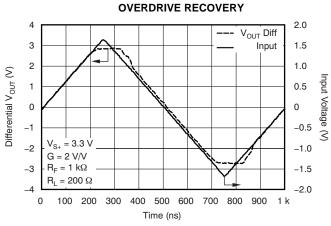


Figure 5.

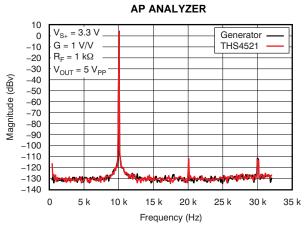


Figure 6.



At V_{S+} = +3.3 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

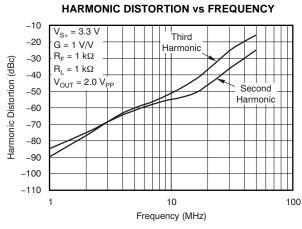


Figure 7.

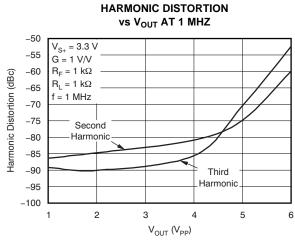


Figure 8.

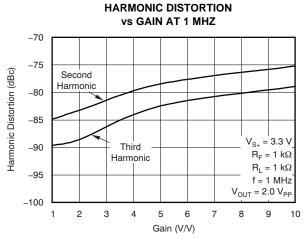


Figure 9.

HARMONIC DISTORTION

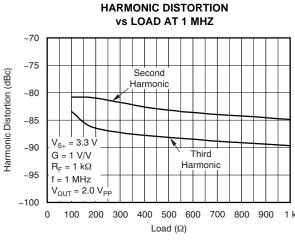
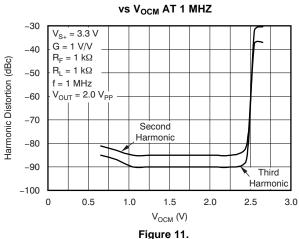


Figure 10.

TWO-TONE INTERMODULATION DISTORTION



.0

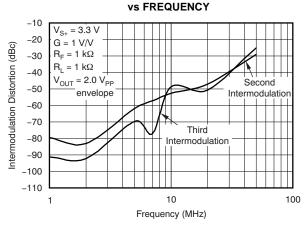


Figure 12.



At V_{S+} = +3.3 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

SINGLE-ENDED OUTPUT VOLTAGE SWING vs LOAD RESISTANCE

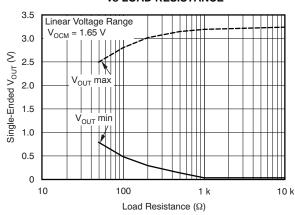


Figure 13.

MAIN AMPLIFIER DIFFERENTIAL OUTPUT IMPEDANCE vs FREQUENCY

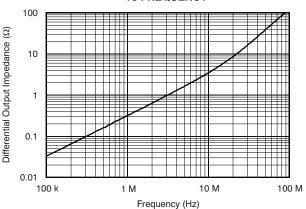
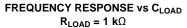


Figure 14.



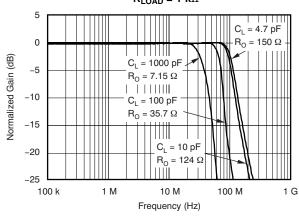


Figure 15.

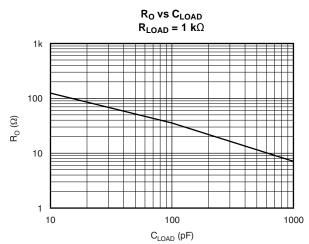


Figure 16.

REJECTION RATIO vs FREQUENCY

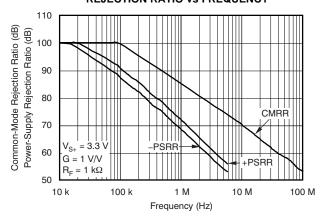


Figure 17.

THS4522, THS4524 CROSSTALK (MEASURED DIFFERENTIALLY)

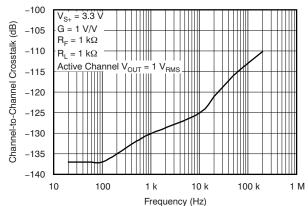


Figure 18.



At V_{S+} = +3.3 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

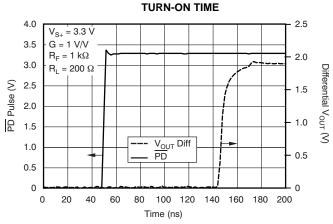


Figure 19.

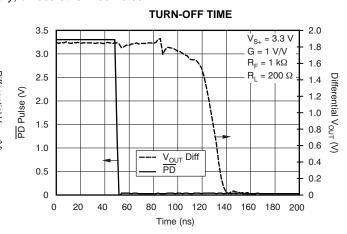


Figure 20.

MAIN AMPLIFIER

INPUT-REFERRED VOLTAGE AND CURRENT NOISE SPECTRAL DENSITY

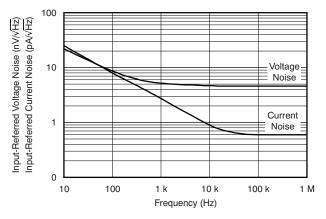


Figure 21.

OUTPUT BALANCE ERROR

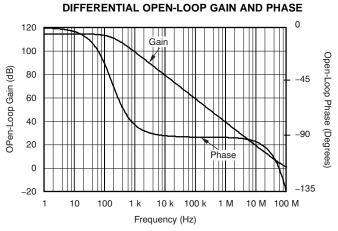


Figure 22.

vs FREQUENCY -20 G = 0 dB-25

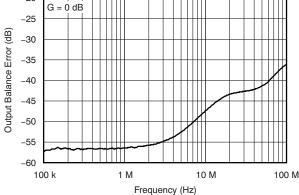


Figure 23.

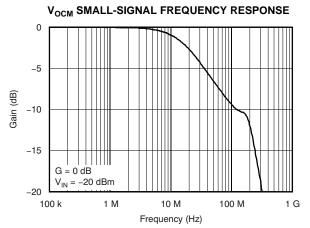
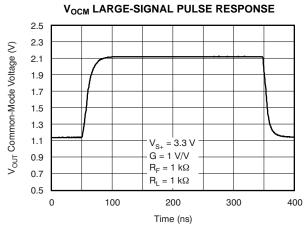


Figure 24.



At V_{S+} = +3.3 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.





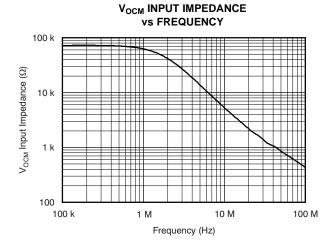


Figure 26.



TYPICAL CHARACTERISTICS: 5 V

At V_{S+} = +5 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_F = 1 k Ω , R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

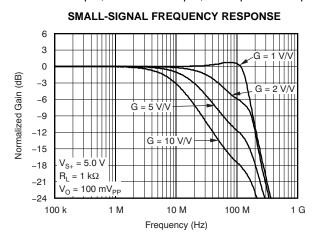


Figure 27.

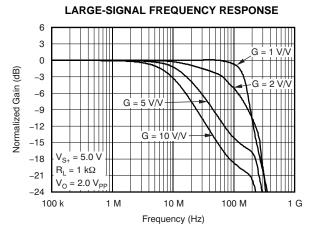
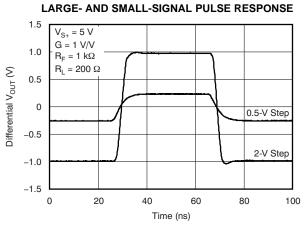
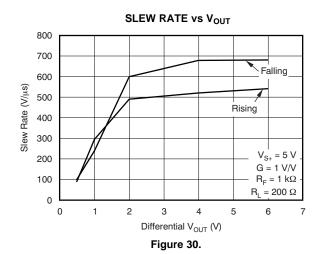


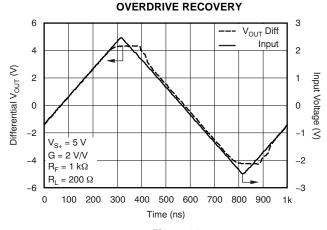
Figure 28.







10-kHz OUTPUT SPECTRUM ON AP ANALYZER AT $V_{OUT} = 8 V_{PP}$





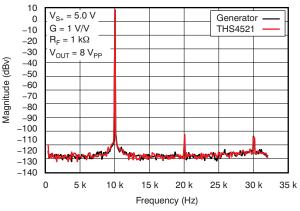


Figure 32.



At V_{S+} = +5 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_F = 1 $k\Omega$, R_L = 1 $k\Omega$ differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

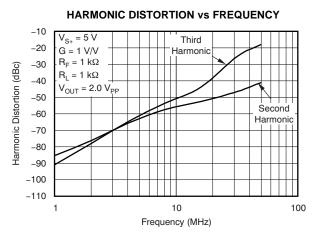


Figure 33.

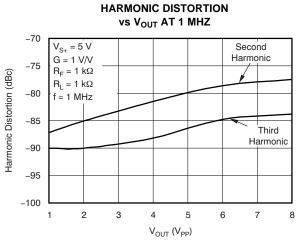


Figure 34.

HARMONIC DISTORTION

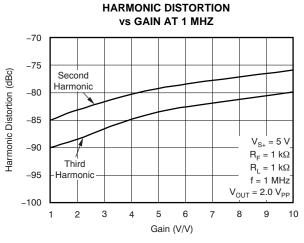


Figure 35.

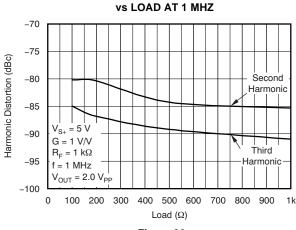
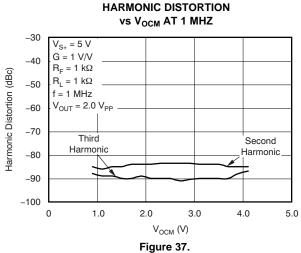


Figure 36.

TWO-TONE INTERMODULATION DISTORTION



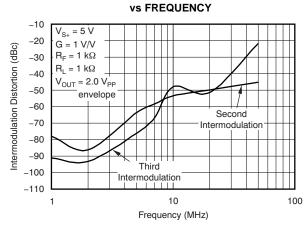
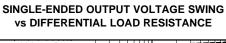


Figure 38.



At V_{S+} = +5 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_F = 1 k Ω , R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.



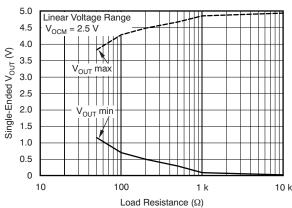


Figure 39.

MAIN AMPLIFIER DIFFERENTIAL OUTPUT IMPEDANCE vs FREQUENCY

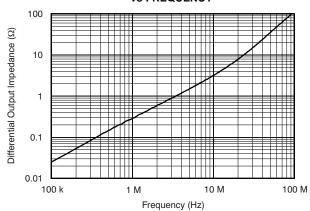


Figure 40.



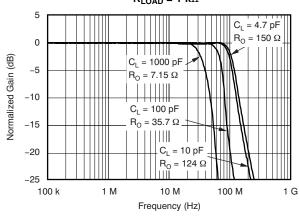


Figure 41.

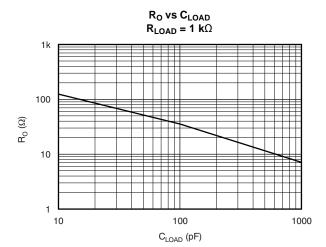


Figure 42.

REJECTION RATIO vs FREQUENCY

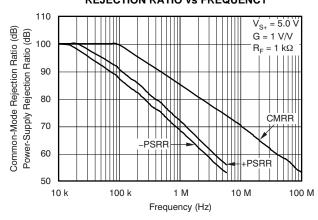


Figure 43.

THS4522, THS4524 CROSSTALK (MEASURED DIFFERENTIALLY)

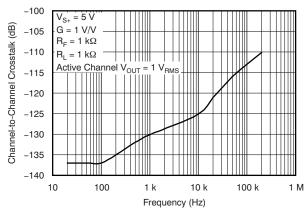


Figure 44.



At V_{S+} = +5 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_F = 1 $k\Omega$, R_L = 1 $k\Omega$ differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.

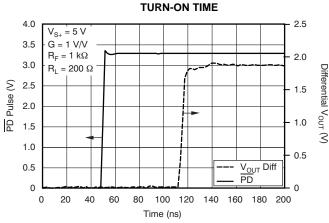


Figure 45.

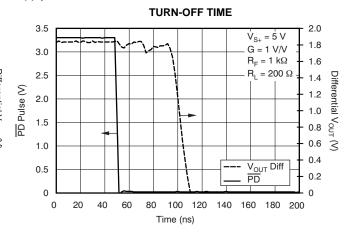


Figure 46.

MAIN AMPLIFIER

INPUT-REFERRED VOLTAGE AND CURRENT NOISE SPECTRAL DENSITY

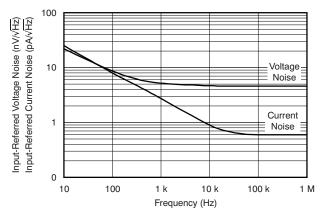


Figure 47.

OUTPUT BALANCE ERROR

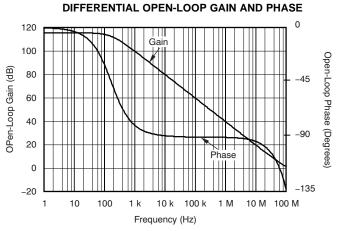


Figure 48.

vs FREQUENCY -20 G = 0 dB-25 Output Balance Error (dB) -30

Frequency (Hz) Figure 49.

10 M

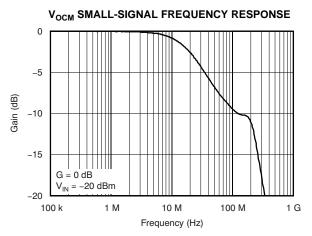


Figure 50.

1 M

-35

-40

-45 -50

-55

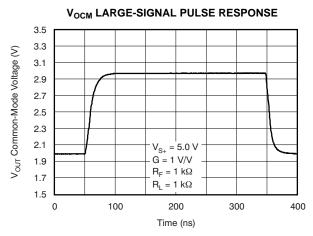
-60

100 k

100 M



At V_{S+} = +5 V, V_{S-} = 0 V, V_{OCM} = open, V_{OUT} = 2 V_{PP} (differential), R_F = 1 k Ω , R_L = 1 k Ω differential, G = 1 V/V, single-ended input, differential output, and input and output referenced to midsupply, unless otherwise noted.





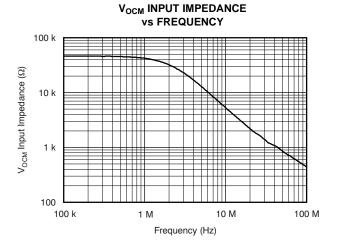


Figure 52.



TEST CIRCUITS

Overview

The THS4521, THS4522, and THS4524 family is tested with the test circuits shown in this section; all circuits are built using the available THS4521 evaluation module (EVM). For simplicity. power-supply decoupling is not shown; see the layout in the Applications section for recommendations. Depending on the test conditions, component values change in accordance with Table 1 and Table 2, or as otherwise noted. In some cases the signal generators used are ac-coupled and in others they dc-coupled $50-\Omega$ sources. To balance the amplifier when ac-coupled, a $0.22-\mu F$ capacitor and $49.9-\Omega$ resistor to ground are inserted across RIT on the alternate input; when dc-coupled, only the $49.9-\Omega$ resistor to ground is added across R_{IT}. A split power supply is used to ease the interface to common test equipment, but the amplifier can be operated in a single-supply configuration as described in the Applications section with no impact on performance. Also, for most of the tests, except as noted, the devices are tested with single-ended inputs and a transformer on the output to convert the differential output to single-ended because common lab test equipment has single-ended inputs and outputs. Similar or better performance can be expected with differential inputs and outputs.

As a result of the voltage divider on the output formed by the load component values, the amplifier output is attenuated. The *Atten* column in Table 2 shows the attenuation expected from the resistor divider. When using a transformer at the output (as shown in Figure 54), the signal sees slightly more loss because of transformer and line loss; these numbers are approximate.

Table 1. Gain Component Values for Single-Ended Input⁽¹⁾

Gain	R _F	R_{G}	R _{IT}
1 V/V	1 kΩ	1 kΩ	52.3 Ω
2 V/V	1 kΩ	487 Ω	53.6 Ω
5 V/V	1 kΩ	187 Ω	59.0 Ω
10 V/V	1 kΩ	86.6 Ω	69.8 Ω

1. Gain setting includes $50-\Omega$ source impedance. Components are chosen to achieve gain and $50-\Omega$ input termination.

Table 2. Load Component Values For 1:1
Differential to Single-Ended Output Transformer⁽¹⁾

R_L	Ro	R _{OT}	Atten
100 Ω	24.9 Ω	Open	6 dB
200 Ω	86.6 Ω	69.8 Ω	16.8 dB
499 Ω	237 Ω	56.2 Ω	25.5 dB
1 kΩ	487 Ω	52.3 Ω	31.8 dB

1. Total load includes $50-\Omega$ termination by the test equipment. Components are chosen to achieve load and $50-\Omega$ line termination through a 1:1 transformer.

Frequency Response

The circuit shown in Figure 53 is used to measure the frequency response of the circuit.

An HP network analyzer is used as the signal source and the measurement device. The output impedance of the HP network analyzer is is dc-coupled and is 50 $\Omega.\ R_{IT}$ and R_G are chosen to impedance-match to 50 Ω and maintain the proper gain. To balance the amplifier, a $49.9\text{-}\Omega$ resistor to ground is inserted across R_{IT} on the alternate input.

The output is probed using a Tektronix high-impedance differential probe across the 953- Ω resistor and referred to the amplifier output by adding back the 0.42-dB because of the voltage divider on the output.

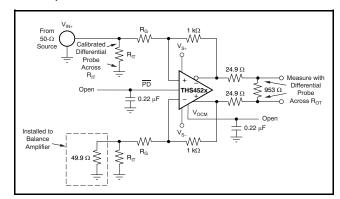


Figure 53. Frequency Response Test Circuit



Distortion

The circuit shown in Figure 54 is used to measure harmonic and intermodulation distortion of the amplifier.

An HP signal generator is used as the signal source and the output is measured with a Rhode and Schwarz spectrum analyzer. The output impedance of the HP signal generator is ac-coupled and is 50 Ω . R_{IT} and R_{G} are chosen to impedance match to 50 Ω and maintain the proper gain. To balance the amplifier, a 0.22- μF capacitor and 49.9- Ω resistor to ground are inserted across R_{IT} on the alternate input.

A low-pass filter is inserted in series with the input to reduce harmonics generated at the signal source. The level of the fundamental is measured and then a high-pass filter is inserted at the output to reduce the fundamental so it does not generate distortion in the input of the spectrum analyzer.

The transformer used in the output to convert the signal from differential to single-ended is an ADT1-1WT. It limits the frequency response of the circuit so that measurements cannot be made below approximately 1 MHz.

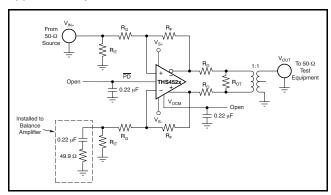


Figure 54. Distortion Test Circuit

Slew Rate, Transient Response, Settling Time, Output Impedance, Overdrive, Output Voltage, and Turn-On/Turn-Off Time

The circuit shown in Figure 55 is used to measure slew rate, transient response, settling time, output impedance, overdrive recovery, output voltage swing, and amplifer turn-on/turn-off time. Turn-on and turn-off time are measured with the same circuit modified for $50\text{-}\Omega$ input impedance on the \overline{PD} input by replacing the $0.22\text{-}\mu\text{F}$ capacitor with a $49.9\text{-}\Omega$ resistor. For output impedance, the signal is injected at V_{OUT} with V_{IN} open; the drop across the 2x $49.9\text{-}\Omega$ resistors is then used to calculate the impedance seen looking into the amplifier output.

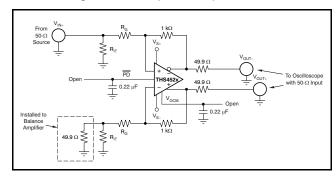


Figure 55. Slew Rate, Transient Response, Settling Time, Output Impedance, Overdrive Recovery, V_{OUT} Swing, and Turn-On/Turn-Off Test Circuit

Common-Mode and Power-Supply Rejection

The circuit shown in Figure 56 is used to measure the CMRR. The signal from the network analyzer is applied common-mode to the input. Figure 57 is used to measure the PSRR of V_{S+} and V_{S-} . The power supply under test is applied to the network analyzer dc offset input. For both CMRR and PSRR, the output is probed using a Tektronix high-impedance differential probe across the 953- Ω resistor and referred to the amplifier output by adding back the 0.42-dB as a result of the voltage divider on the output. For these tests, the resistors are matched for best results.

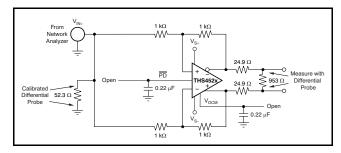


Figure 56. CMRR Test Circuit

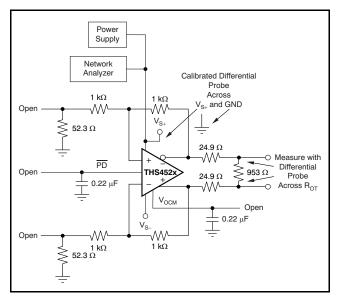


Figure 57. PSRR Test Circuit

V_{ocm} Input

The circuit illustrated in Figure 58 is used to measure the frequency response and input impedance of the $V_{\rm OCM}$ input. Frequency response is measured using a Tektronix high-impedance differential probe, with $R_{\rm CM}=0~\Omega$ at the common point of $V_{\rm OUT+}$ and $V_{\rm OUT-}$, formed at the summing junction of the two matched 499- Ω resistors, with respect to ground. The input impedance is measured using a Tektronix high-impedance differential probe at the $V_{\rm OCM}$ input with $R_{\rm CM}=10~{\rm k}\Omega$ and the drop across the $10{\rm k}\Omega$ resistor is used to calculate the impedance seen looking into the amplifier $V_{\rm OCM}$ input.

The circuit shown in Figure 59 measures the transient response and slew rate of the V_{OCM} input. A 1-V step input is applied to the V_{OCM} input and the output is measured using a $50-\Omega$ oscilloscope input referenced back to the amplifier output.

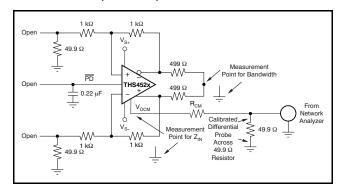


Figure 58. V_{OCM} Input Test Circuit

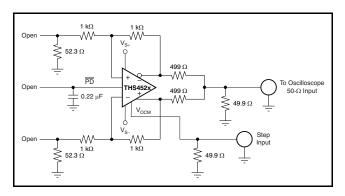


Figure 59. V_{OCM} Transient Response and Slew Rate Test Circuit



APPLICATION INFORMATION

The following circuits show application information for the THS4521, THS4522, and THS4524 family. For simplicity, power-supply decoupling capacitors are not shown in these diagrams; see the *EVM and Layout Recommendations* section for suggested guidelines. For more details on the use and operation of fully differential op amps, refer to the Application Report *Fully-Differential Amplifiers* (SLOA054), available for download from the TI web site at www.ti.com.

Differential Input to Differential Output Amplifier

The THS4521, THS4522, and THS4524 family are fully-differential operational amplifiers that can be used to amplify differential input signals to differential output signals. Figure 60 shows <u>a</u> basic block diagram of the circuit (V_{OCM} and \overline{PD} inputs not shown). The gain of the circuit is set by R_F divided by R_G .

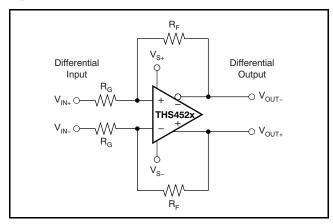


Figure 60. Differential Input to Differential Output Amplifier

Single-Ended Input to Differential Output Amplifier

The THS4521, THS4522, and THS4524 family can also amplify and convert single-ended input signals to differential output signals. Figure 61 illustrates a basic block diagram of the circuit (V_{OCM} and $\overline{\text{PD}}$ inputs not shown). The gain of the circuit is again set by R_{F} divided by R_{G} .

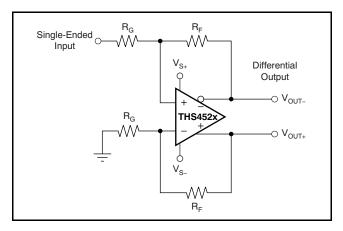


Figure 61. Single-Ended Input to Differential Output Amplifier

Input Common-Mode Voltage Range

The input common-mode voltage of a fully-differential op amp is the voltage at the + and – input pins of the device.

It is important to not violate the input common-mode voltage range (V_{ICR}) of the op amp. Assuming the op amp is in linear operation, the voltage across the input pins is only a few millivolts at most. Therefore, finding the voltage at one input pin determines the input common-mode voltage of the op amp.

Treating the negative input as a summing node, the voltage is given by Equation 1:

$$\left[V_{OUT_{+}} \times \frac{R_{G}}{R_{G} + R_{F}}\right] + \left[V_{IN_{-}} \times \frac{R_{F}}{R_{G} + R_{F}}\right]$$
(1)

To determine the V_{ICR} of the op amp, the voltage at the negative input is evaluated at the extremes of V_{OUT+} . As the gain of the op amp increases, the input common-mode voltage becomes closer and closer to the input common-mode voltage of the source.

Setting the Output Common-Mode Voltage

The output common-model voltage is set by the voltage at the $V_{\rm OCM}$ pin. The internal common-mode control circuit maintains the output common-mode voltage within 5-mV offset (typ) from the set voltage. If left unconnected, the common-mode set point is set to midsupply by internal circuitry, which may be overdriven from an external source.

Figure 62 represents the V_{OCM} input. The internal V_{OCM} circuit has typically 23 MHz of -3 dB bandwidth, which is required for best performance, but it is intended to be a dc bias input pin. A 0.22- μ F bypass capacitor is recommended on this pin to reduce noise. The external current required to overdrive the internal resistor divider is given approximately by the formula in Equation 2:

$$I_{\text{EXT}} = \ \frac{2V_{\text{OCM}} - (V_{\text{S+}} - V_{\text{S-}})}{50 \ k\Omega}$$

where:

V_{OCM} is the voltage applied to the V_{OCM} pin
 (2)

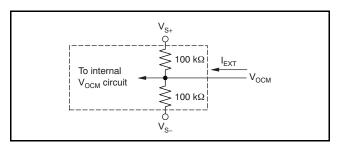


Figure 62. V_{OCM} Input Circuit

Typical Performance Variation with Supply Voltage

The THS4521, THS4522, and THS4524 family of devices provide excellent performance across the specified power-supply range of 2.5 V to 5.5 V with only minor variations. The input and output voltage compliance ranges track with the power supply in nearly a 1:1 correlation. Other changes can be observed in slew rate, output current drive, open-loop gain, bandwidth, and distortion. Table 3 shows the typical variation to be expected in these key performance parameters.

Single-Supply Operation

To facilitate testing with common lab equipment, the THS4521EVM allows for split-supply operation; most of the characterization data presented in this data sheet is measured using split-supply power inputs. The device can easily be used with a single-supply power input without degrading performance.

Figure 63 shows a dc-coupled single-supply circuit with single-ended inputs. This circuit can also be applied to differential input sources.

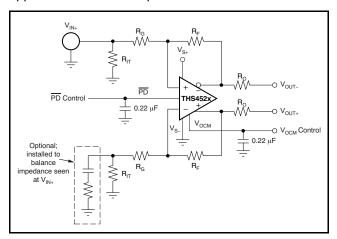


Figure 63. THS4521 DC-Coupled Single-Supply with Single-Ended Inputs

The input common-mode voltage range of the THS4521, THS4522, and THS4524 family is designed to include the negative supply voltage. in the circuit shown in Figure 63, the signal source is referenced to ground. $V_{\rm OCM}$ is set by an external control source or, if left unconnected, the internal circuit defaults to midsupply. Together with the input impedance of the amplifier circuit, $R_{\rm IT}$ provides input termination, which is also referenced to ground.

Note that R_{IT} and optional matching components are added to the alternate input to balance the impedance at signal input.

Table 3. Typical Performance Variation versus Power-Supply Voltage

PARAMETER	V _S = 5 V	V _S = 3.3 V	V _S = 2.5 V			
-3-dB Small-signal bandwidth	145 MHz	135 MHz	125 MHz			
Slew rate (2-V step)	490 V/μs	420 V/μs	210 V/µs			
Harmonic distortion at 1 MHz, 2 V_{PP} , $R_L = 1 k\Omega$						
harmonic	-85 dBc	-85 dBc	-84 dBc			
harmonic	-91 dBc	-90 dBc	-88 dBc			
Open-loop gain	119 dB	116 dB	115 dB			
Linear output current drive	55 mA	35 mA	24 mA			



Low-Power Applications and the Effects of Resistor Values on Bandwidth

For low-power operation, it may be necessary to increase the gain setting resistors values to limit current consumption and not load the source. Using larger value resistors lowers the bandwidth of the THS4521, THS4522, and THS4524 family as a result of the interactions between the resistors, the device parasitic capacitance, and printed circuit board (PCB) parasitic capacitance. Figure 64 shows the small-signal frequency response with 1-k Ω , 10-k Ω , and 100-k Ω resistors for R_F, R_G, and R_L (impedance is assumed to typically increase for all three resistors in low-power applications).

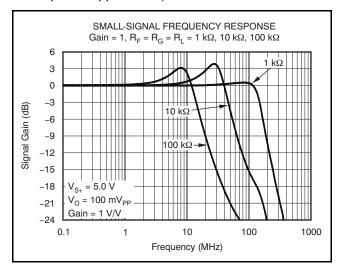


Figure 64. THS4521 Frequency Response with Various Gain Setting and Load Resistor Values

Frequency Response Variation due to Package Options

Users can see variations in the small-signal ($V_{OUT} = 100 \text{ mV}_{PP}$) frequency response between the available package options for the THS4521, THS4522, and THS4524 family as a result of parasitic elements associated with each package and board layout changes. Figure 65 shows the variance measured in the lab; this variance is to be expected even when using a good layout.

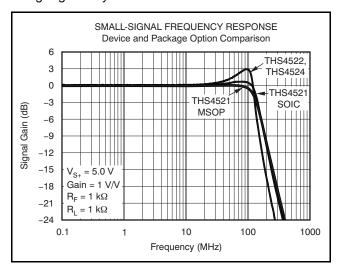


Figure 65. Small-Signal Frequency Response: Package Variations

TEXAS INSTRUMENTS

Driving Capacitive Loads

The THS4521, THS4522, and THS4524 family is designed for a nominal capacitive load of 1 pF on each output to ground. When driving capacitive loads greater than 1 pF, it is recommended to use small resistors (R_O) in series with the output, placed as close to the device as possible. Without R_O, capacitance on the output interacts with the output impedance of the amplifier and causes phase shift in the loop gain of the amplifier that reduces the phase margin. This reduction in phase margin results in frequency response peaking; overshoot, undershoot, and/or ringing when a step or square-wave signal is applied; and may lead to instability or oscillation. Inserting R_O isolates the phase shift from the loop gain path and restores the phase margin, but it also limits bandwidth. Figure 66 shows the recommended values of R_O versus capacitive loads (C_L), and Figure 67 shows an illustration of the frequency response with various values.

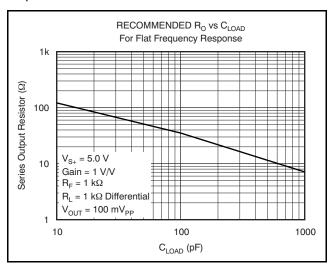


Figure 66. Recommended Series Output Resistor versus Capacitive Load for Flat Frequency Response, with $R_{LOAD} = 1 \text{ k}\Omega$

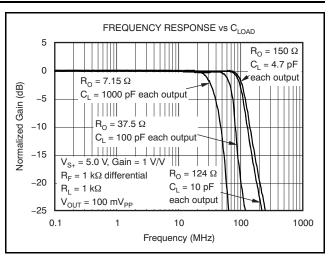


Figure 67. Frequency Response for Various R_O and C_L Values, with R_{LOAD} = 1 $k\Omega$

Audio Performance

The THS4521, THS4522, and THS4524 family provide excellent audio performance with very low quiescent power. To show performance in the audio band, the device was tested with a SYS-2722 audio analyzer from Audio Precision. THD+N and FFT tests were performed at 1-V_{RMS} output voltage. Performance is the same on both 3.3-V and 5-V supplies. Figure 68 shows the test circuit used; see Figure 69 and Figure 70 for the performance of the analyzer using internal loopback mode (generator) together with the THS4521.

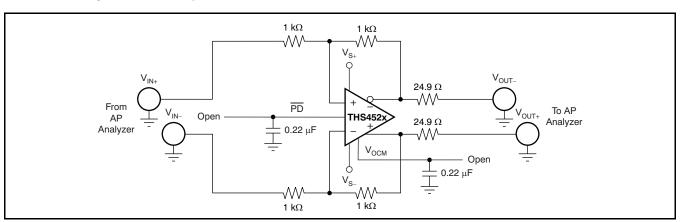


Figure 68. THS4521 AP Analyzer Test Circuit



Note that the harmonic distortion performance is very close to the same with and without the device meaning the THS4521 performance is actually much better than can be directly measured by this meathod. The actual device performance can be estimated by placing the device in a large noise gain and using the reduction in loop gain correction. The THS4521 is placed in a noise gain of 101 by adding a 10-Ω resistor directly across the input terminals of the circuit shown in Figure 68. This test was performed using the AP instrument as both the signal source and the analyzer. The second-order harmonic distortion at 1 kHz is estimated to be -122 dBc with $V_O = 1V_{RMS}$; third-order harmonic distortion is estimated to be -141 dBc. The third-order harmonic distortion result matches exactly with design simulations, but the second-order harmonic distortion is about 10 dB worse. This result is not unexpected second-order distortion because harmonic performance with a differential signal depends heavily on cancellation as a result of the differential nature of the signal, which depends on board layout, bypass capacitors, external cabling, and so forth. Note that the circuit of Figure 68 is also used to measure crosstalk between channels.

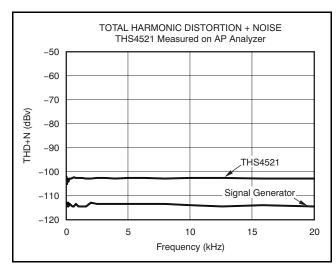


Figure 69. THS4521 1-V_{RMS} 20-Hz to 20-kHz THD+N

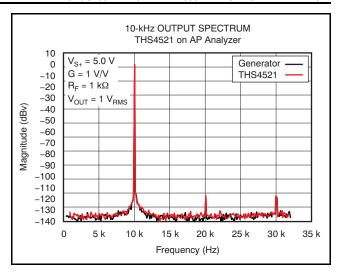


Figure 70. THS4521 1-V_{RMS} 10-kHz FFT Plot

The THS4521 shows even better THD+N performance when driving higher amplitude output, such as 5 V_{PP} that is more typical when driving an ADC. To show performance with an extended frequency range, higher gain, and higher amplitude, the device was tested with 5 V_{PP} up to 80 kHz with the AP. Figure 71 shows the resulting THD+N graph with no weighting.

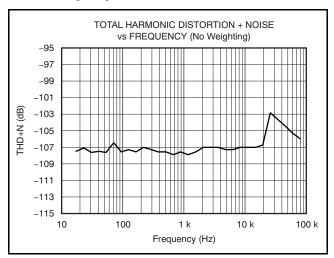


Figure 71. THD+N (No Weighting) on AP, 80-kHz Bandwidth at G = 1 with 5-V_{PP} Output

TEXAS INSTRUMENTS

Audio On/Off Pop Performance

The THS4521 was tested to show on and off pop performance by connecting a speaker between the differential outputs and switching the power supply on and off, and also by using the PD function of the THS4521. Testing was done with and without tones. During these tests, no audible pop could be heard.

With no tone input, Figure 72 shows the pop performance when switching power on to the THS4521 and Figure 73 shows the device performance when turning the power off. The transients during power on and off illustrate that no audible pop should be heard

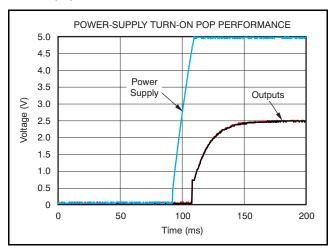


Figure 72. THS4521 Power-Supply Turn-On Pop Performance

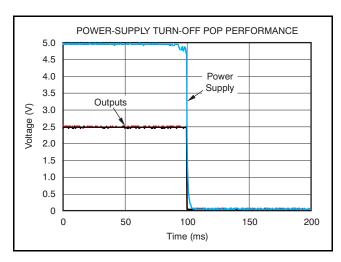


Figure 73. THS4521 Power-Supply Turn-Off Pop Performance

With no tone input, Figure 74 shows the pop performance using the PD pin to enable the THS4521, and Figure 75 shows performance using the PD pin to disable the device. Again, the transients during power on and off show that no audible pop should be heard. It should also be noted that the turn on/off times are faster using the PD pin technique.

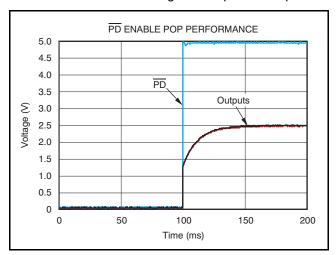


Figure 74. THS4521 PD Pin Enable Pop Performance

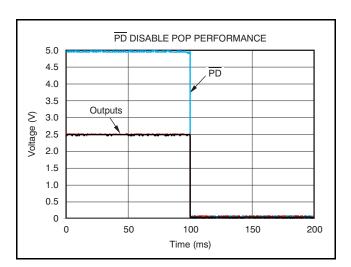


Figure 75. THS4521 PD Pin Disable Pop Performance

The power on/off pop performance of the THS4521, whether by switching the power supply or when using the power-down function built into the chip, shows that no special design should be required to prevent an audible pop.



Audio ADC Driver Performance: THS4521 and PCM4204 Combined Performance

To show achievable performance with high-performance audio ADC, the THS4521 is tested as the drive amplifier for the PCM4204. The PCM4204 is a high-performance, four-channel ADC designed for professional and broadcast audio applications. The PCM4204 architecture uses a 1-bit delta-sigma ($\Delta\Sigma$) modulator per channel that incorporates an advanced dither scheme improved dynamic performance, and supports PCM output data. The PCM4204 provides a flexible serial port interface and many other advanced features. Refer to the PCM4204 product data sheet for more information.

The PCM4204EVM can test the audio performance of the THS4521 as a drive amplifier. The standard PCM4204EVM is provided with four OPA1632 fully-differential amplifiers, which use the same device pinout as the THS4521. For testing, one of these amplifiers is replaced with a THS4521 device in same package (MSOP), and the power supply changes to a single-supply +5V. Figure 78 shows the modifications made to the circuit. Note the resistor connecting the V_{OCM} input of the THS4521 to the input common-mode drive from the PCM4204 is shown removed and is optional; no performance change was noted with it connected or removed. The THS4521 is operated with a +5-V single-supply so the output common-mode defaults to +2.5 V as required at the input of the PCM4204. The EVM power connections were modified by connecting positive supply inputs,

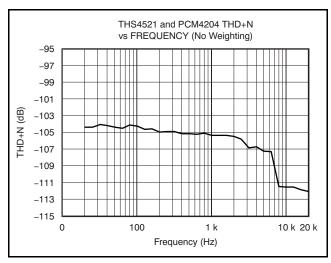


Figure 76. THS4521 and PCM4204: THD+N versus Frequency with No Weighting

+15 V, +5 VA and +5 VD, to a +5-V external power supply (EXT +3.3 was not used) and connecting -15 V and all ground inputs to ground on the external power supply. Note only one external +5-V supply was needed to power all devices on the EVM.

A SYS-2722 Audio Analyzer from Audio Precision (AP) provides an analog audio input to the EVM; the PCM-formatted digital output is read by the digital input on the AP.

Data were taken using a $256-f_S$ system clock to achieve $f_S = 48$ -kHz measurements, and audio output uses PCM format. Other data rates and formats are expected to show similar performance in line with that shown in the product data sheet.

Figure 76 shows the THD+N vs Frequency response with no weighting; Figure 77 shows an FFT of the output with 1-kHz input tone. Input signals to the PCM4204 for these tests is 0.5 dBFS. Dynamic range is also tested at -60 dBFS, $f_{\rm IN}=1$ kHz, and A-weighted. Table 4 summarizes testing results using the THS4521 together with the PCM4204 versus typical data sheet performance measurements, and show that it make an excellent drive amplifier for this ADC.

The test circuit shown in Figure 78 has a gain = 0.27 and attenuates the input signal. For applications that require higher gain, the circuit was modified to gains of G = 1, G = 2, and G = 5 by replacing the feedback resistors (R33 and R34) and re-tested to show performance.

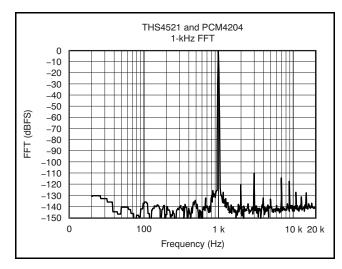


Figure 77. THS4521 and PCM4204 1-kHz FFT



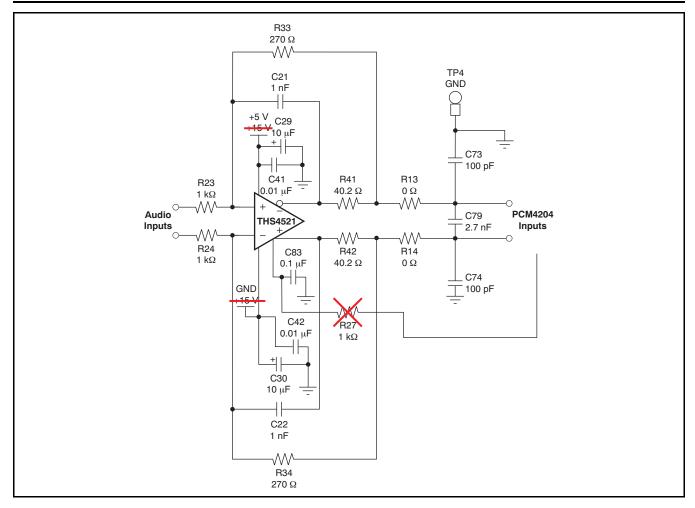


Figure 78. THS4521 and PCM4204 Test Circuit

Table 4. 1-kHz AC Analysis: Test Circuit versus PCM4204 Data Sheet Typical Specifications ($f_S = 48 \text{ kSPS}$)

Configuration	Tone	THD+N	Dynamic Range	
THS4521 and PCM4204	1 kHz	-106 dBc	117 dB	
PCM4204 Data sheet (typ)	1 kHz	-105 dBc	118 dB	



Figure 79 shows the THS4521 and PCM4204 THD+N versus frequency with no weighting at higher gains.

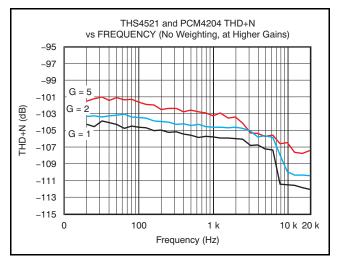


Figure 79. THS4521 and PCM4204: THD+N versus Frequency with No Weighting at Higher Gains

Audio ADC Driver Performance: THS4521 and PCM3168 Combined Performance

The THS4521 is also tested as the drive amplifier for the PCM3168A ADC input. The PCM3168A is a high-performance, single-chip, 24-bit, 6-in/8-out, audio coder/decoder (codec) with single-ended and differential selectable analog inputs and differential outputs. The six-channel, 24-bit ADC employs a $\Delta\Sigma$ modulator and supports 8-kHz to 96-kHz sampling rates and a 16-bit/24-bit width digital audio output word on the audio interface. The eight-channel, 24-bit digital-to-analog converter (DAC) employs a $\Delta\Sigma$ modulator and supports 8-kHz to 192-kHz sampling rates and a 16-bit/24-bit width digital audio input word on the audio interface. Each audio interface supports I²S™, left-/right-justified, and DSP formats with 16-bit/24-bit word width. In addition, the PCM3168A supports the time-division-multiplexed (TDM) format.. The PCM3168A provides flexible serial port interface and many other advanced features. Refer to the PCM3168A product data sheet for more information.

The PCM3168A EVM is used to test the audio performance of the THS4521 as a drive amplifier. The standard PCM3168A EVM is provided with OPA2134 op amps that are used to convert single-ended inputs to differential to drive the ADC. For testing, the op amp output series resistors are removed from one of the channels and a THS4521, mounted on its standard EVM, is connected to the ADC inputs via short coaxial cables. The THS4521

EVM is configured for both differential inputs as shown in Figure 60 and for single-ended input as shown in Figure 61 with 1-k Ω resistors for R_F and R_G, and $24.9-\Omega$ resistors in series with each output to isolate the outputs from the reactive load of the coaxial cables. To limit the noise from the external EVM and cables, a 2.7-nF capacitor is placed differentially across the PCM3168A inputs. The THS4521 is operated with a single-supply +5-V supply so the output common-mode of the THS4521 defaults to +2.5 V as required at the input of the PCM3168A. The PCM3168A EVM is configured and operated as described in the PCM3168AEVM User Guide. The ADC was tested with an external THS4521 EVM with both single-ended input and differential inputs. In both configurations, the results are the same. Figure 80 shows the THD+N versus frequency and Table 5 compares the result to the PCM3168 data sheet typical specification at 1 kHz. Both graphs show that it makes an excellent drive amplifier for this ADC. Note: a 2700 series Audio Analyzer from Audio Precision is used to generate the input signals to the THS4521 and to analyze the digital data from the PCM3168.

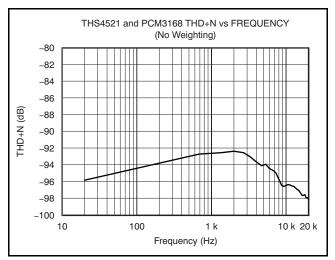


Figure 80. THS4521 and PCM3168: THD+N versus Frequency with No Weighting

Table 5. 1-kHz AC Analysis: Test Circuit vs PCM3168 Data Sheet Typical Specifications (f_S = 48 kSPS)

Configuration	Tone	THD+N
THS4521 and PCM3168	1 kHz	-92.6 dBc
PCM3168 Data sheet (typ)	1 kHz	–93 dBc



ADC Driver Performance: THS4521 and ADS1278 Combined Performance

The THS4521 provides excellent performance when driving high-performance $\Delta\Sigma$ and successive approximation register (SAR) ADCs in audio and industrial applications using a single 3-V to 5-V power supply. To show achievable performance, the THS4521 is tested as the drive amplifier for the ADS1278 24-bit ADC. The ADS1278 offers excellent ac and dc performance, with four selectable operating

modes from 10 kSPS to 128 kSPS to enable the user to fine-tune performance and power for specific application needs. The circuit shown in Figure 81 was used to test the performance. Data were taken using the High-Resolution mode (52 kSPS) of the ADS1278 with input frequencies at 1 kHz and 10 kHz and signal levels 1/2 dB below full-scale (-0.5 dBFS). FFT plots showing the spectral performance are given in Figure 82 and Figure 83; tabulated ac analysis results are shown in Table 6 and compared to the ADS1278 data sheet typical performance specifications.

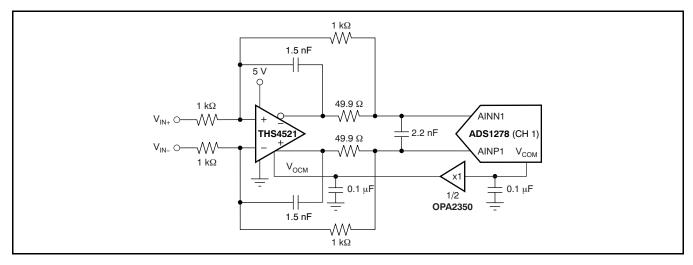
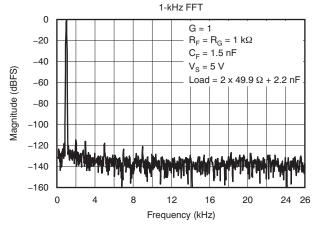


Figure 81. THS4521 and ADS1278 (Ch 1) Test Circuit





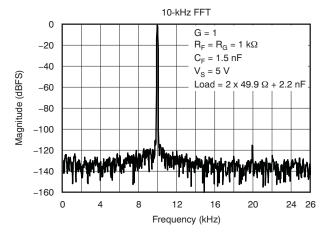


Figure 83. 10-kHz FFT

Table 6. AC Analysis

Configuration	Tone	Signal (dBFS)	SNR (dBc)	THD (dBc)	SINAD (dBc)	SFDR (dBc)
THS4521and	1 kHz	-0.5	109	-108	105	114
ADS1278	10 kHz	-0.5	102	-110	101	110
ADS1278 Data sheet (typ)	1 kHz	-0.5	110	-108	_	109



ADC Driver Performance: THS4521 and ADS8321 Combined Performance

To demonstrate achievable performance, the THS4521 is tested as the drive amplifier for the ADS8321 16-bit SAR ADC. The ADS8321 offers excellent ac and dc performance, with ultra-low power and small size. The circuit shown in Figure 84 was used to test the performance.

Data were taken using the ADS8321 at 100 kSPS with input frequencies of 2 kHz and 10 kHz and signal levels that were -0.5 dBFS. FFT plots that illustrate the spectral performance are given in Figure 85 and Figure 86. Tabulated ac analysis results are listed in Table 7 and compared to the ADS8321 data sheet typical performance.

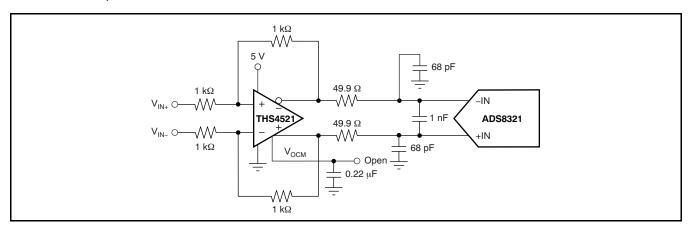
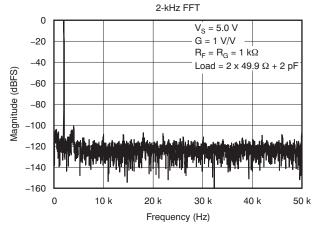


Figure 84. THS4521 and ADS8321 Test Circuit



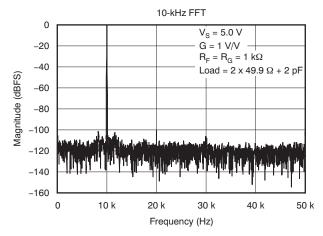


Figure 85. 2-kHZ FFT

Figure 86. 10-kHz FFT

Table 7. AC Analysis

Configuration	Tone	Signal (dBFS)	SNR (dBc)	THD (dBc)	SINAD (dBc)	SFDR (dBc)
THS4521 and	2 kHz	-0.5	86.7	-97.8	86.4	100.7
ADS8321	10 kHz	-0.5	85.2	-98.1	85.2	102.2
ADS8321 Data sheet (typ)	10 kHz	-0.5	87	-86	84	86



EVM AND LAYOUT RECOMMENDATIONS

Figure 87 shows the THS4521EVM schematic. PCB layers 1 through 4 are shown in Figure 88; Table 8 lists the bill of materials for the THS4521EVM as supplied from TI. It is recommended to follow the layout of the external components near to the amplifier, ground plane construction, and power routing as closely as possible. Follow these general guidelines:

- 1. Signal routing should be direct and as short as possible into and out of the op amp circuit.
- 2. The feedback path should be short and direct.
- 3. Ground or power planes should be removed from directly under the amplifier input and output pins.
- 4. An output resistor is recommended in each output lead, placed as near to the output pins as possible.
- 5. Two 0.1-µF power-supply decoupling capacitors should be placed as near to the power-supply pins as possible.
- 6. Two 10-μF power-supply decoupling capacitors should be placed within 1 inch of the device and can be shared among multple analog devices.
- 7. A 0.22- μF capacitor should be placed between the V_{OCM} input pin and ground near to the pin. This capacitor limits noise coupled into the pin.
- 8. The \overline{PD} pin uses TTL logic levels; a bypass capacitor is not necessary if actively driven, but can be used for robustness in noisy environments whether driven or not.
- 9. If input termination resistors R_{10} and R_{11} are used, a single point connection to ground on L2 is recommended.

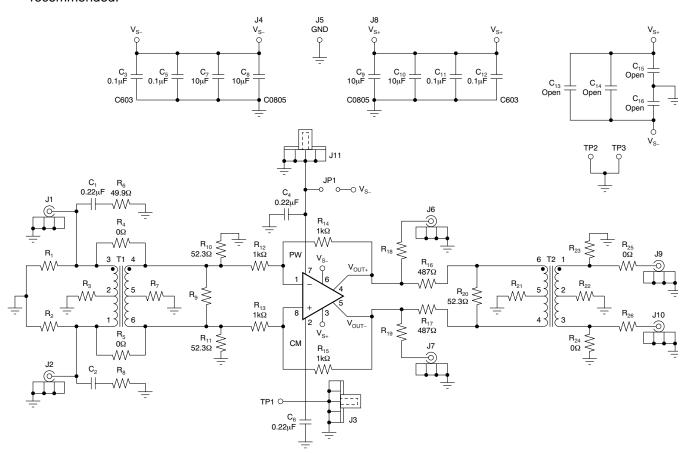


Figure 87. THS4521EVM: Schematic



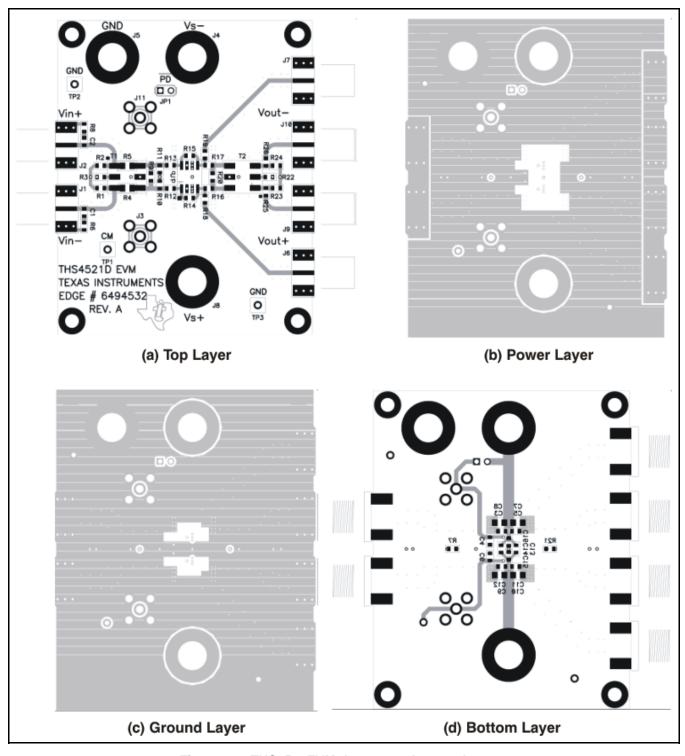


Figure 88. THS4521EVM: Layer 1 to Layer 4 Images



Table 8. THS4521EVM Parts List

ITEM	DESCRIPTION	SMD SIZE	REFERENCE DESIGNATOR	QTY	MANUFACTURER PART NUMBER
1	Capacitor, 10.0 µF, ceramic, X5R, 6.3 V	0805	C7, C8, C9, C10	4	(AVX) 08056D106KAT2A
2	Capacitor, 0.1 µF, ceramic, X7R, 16 V	0603	C3, C5, C11, C12	4	(AVX) 0603YC104KAT2A
3	Capacitor, 0.22 µF, ceramic, X7R, 10 V	0603	C1, C4, C6	3	(AVX) 0603ZC224KAT2A
4	Open	0603	C2, C13, C14, C15, C16	5	
5	Open	0603	R1, R2, R3, R7, R8, R9, R18, R19, R21, R22, R23, R26	12	
6	Resistor, 0 Ω	0603	R24, R25	2	(ROHM) MCR03EZPJ000
7	Resistor, 49.9 Ω, 1/10W, 1%	0603	R6	1	(ROHM) MCR03EZPFX49R9
8	Resistor, 52.3 Ω, 1/10W, 1%	0603	R10, R11, R20	3	(ROHM) MCR03EZPFX52R3
9	Resistor, 487 Ω, 1/10W, 1%	0603	R16, R17	2	(ROHM) MCR03EZPFX4870
10	Resistor, 1k Ω, 1/10W, 1%	0603	R12, R13, R14, R15	4	(ROHM) MCR03EZPFX1001
11	Resistor, 0 Ω	0805	R4, R5	2	(ROHM) MCR10EZPJ000
12	Open		T1	1	
13	Transformer, RF		T2	1	(MINI-CIRCUITS) ADT1-1WT
14	Jack, Banana receptance, 0.25-in dia. hole		J4, J5, J8	3	(SPC) 813
15	Open		J1, J3, J6, J7, J10, J11	6	
16	Connector, edge, SMA PCB jack		J2, J9	2	(JOHNSON) 142-0701-801
17	Header, 0.1 in CTRS, 0.025-in sq. pins	2 POS.	JP1	1	(SULLINS) PBC36SAAN
18	Shunts		JP1	1	(SULLINS) SSC02SYAN
19	Test point, Red		TP1	1	(KEYSTONE) 5000
20	Test point, Black		TP2, TP3	2	(KEYSTONE) 5001
21	IC, THS4521		U1	1	(TI) THS4521D
22	Standoff, 4-40 hex, 0.625 in length			4	(KEYSTONE) 1808
23	Screw, Phillips, 4-40, .250 in			4	SHR-0440-016-SN
24	Board, printed circuit			1	(TI) EDGE# 6494532



REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

C	hanges from Revision E (December 2010) to Revision F	Page
•	Changed Input Offset Current values in 3.3 V Electrical Characteristics	3
•	Changed Input Offset Current Drift values in 3.3 V Electrical Characteristics	3
•	Changed Input Offset Current values in 5 V Electrical Characteristics	6
•	Changed Input Offset Current Drift values in 5 V Electrical Characteristics	6
<u>.</u>	Changed R41 and R42 in Figure 78	32
C	hanges from Revision D (August 2010) to Revision E	Page
•	Changed test level indication for 5-V input offset voltage drift from B to C	5



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EVM Warnings and Restrictions

It is important to operate this EVM within the input voltage range of 3 V to 5.5 V and the output voltage range of 3 V to 5.5 V.

Exceeding the specified input range may cause unexpected operation and/or irreversible damage to the EVM. If there are questions concerning the input range, please contact a TI field representative prior to connecting the input power.

Applying loads outside of the specified output range may result in unintended operation and/or possible permanent damage to the EVM. Please consult the EVM User's Guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative.

During normal operation, some circuit components may have case temperatures greater than +85°C. The EVM is designed to operate properly with certain components above +85°C as long as the input and output ranges are maintained. These components include but are not limited to linear regulators, switching transistors, pass transistors, and current sense resistors. These types of devices can be identified using the EVM schematic located in the EVM User's Guide. When placing measurement probes near these devices during operation, please be aware that these devices may be very warm to the touch.

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18-Oct-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
THS4521ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TH4521	Samples
THS4521IDGKR	ACTIVE	VSSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	4521	Samples
THS4521IDGKT	ACTIVE	VSSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU CU NIPDAUAG	Level-2-260C-1 YEAR	-40 to 85	4521	Samples
THS4521IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	TH4521	Samples
THS4522IPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	THS4522	Samples
THS4522IPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	THS4522	Samples
THS4524IDBT	ACTIVE	TSSOP	DBT	38	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	THS4524	Samples
THS4524IDBTR	ACTIVE	TSSOP	DBT	38	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	THS4524	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.



PACKAGE OPTION ADDENDUM

18-Oct-2013

- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF THS4521, THS4524:

Enhanced Product: THS4524-EP

NOTE: Qualified Version Definitions:

• Enhanced Product - Supports Defense, Aerospace and Medical Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





Α0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

All dimensions are nominal												
Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
THS4521IDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
THS4521IDGKT	VSSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
THS4521IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
THS4522IPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

7 III GITTIOTIOTOTIO GITO TIOTITICA							
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
THS4521IDGKR	VSSOP	DGK	8	2500	367.0	367.0	35.0
THS4521IDGKT	VSSOP	DGK	8	250	210.0	185.0	35.0
THS4521IDR	SOIC	D	8	2500	367.0	367.0	35.0
THS4522IPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

DGK (S-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 per end.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.50 per side.
- E. Falls within JEDEC MO-187 variation AA, except interlead flash.



DGK (S-PDSO-G8)

PLASTIC SMALL OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



DBT (R-PDSO-G38)

PLASTIC SMALL OUTLINE



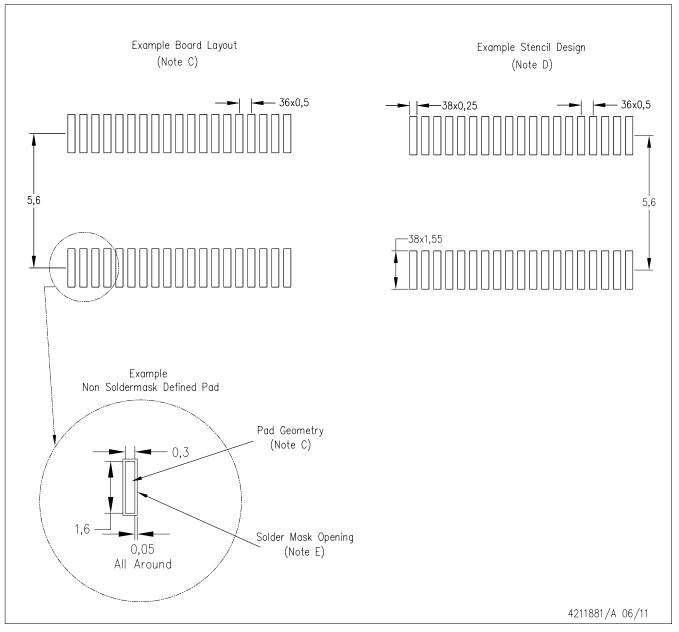
NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-153.



DBT (R-PDSO-G38)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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